

**S/N 10/623,788**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Leonard Forbes et al.	Examiner:	Pamela E. Perkins
Serial No.:	10/623,788	Group Art Unit:	2822
Filed:	July 21, 2003	Docket:	1303.109US1
Title:	STRAINED SEMICONDUCTOR BY FULL WAFER BONDING		

**COMMUNICATION CONCERNING RELATED APPLICATION**

**MS RCE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
11/707,214	February 13, 2007	1303.089US3	MICRO-MECHANICALLY STRAINED SEMICONDUCTOR FILM

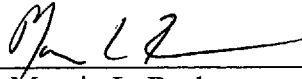
Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

LEONARD FORBES ET AL.

By Applicants' Representatives,

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Date 6-26-07 By   
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 26 day of June, 2007.

  
Name

  
Signature